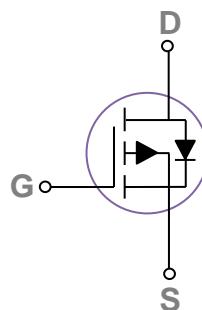
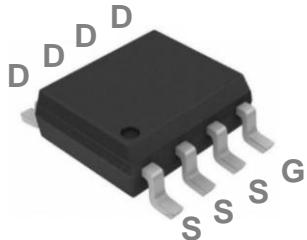


General Description

These P-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

SOP8 Pin Configuration



BVDSS	RDSON	ID
-60V	30mΩ	-8.5A

Features

- -60V, -8.5A, RDS(ON) = 30mΩ@VGS = -10V
- Fast switching
- Green Device Available
- Suit for -4.5V Gate Drive Applications

Applications

- POL Applications
- Load Switch
- LED Application

Absolute Maximum Ratings $T_c=25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Rating	Units
V _{Ds}	Drain-Source Voltage	-60	V
V _{Gs}	Gate-Source Voltage	±20	V
I _D	Drain Current – Continuous ($T_c=25^\circ\text{C}$)	-8.5	A
	Drain Current – Continuous ($T_c=100^\circ\text{C}$)	-5.4	A
I _{DM}	Drain Current – Pulsed ¹	-34	A
EAS	Single Pulse Avalanche Energy ²	105	mJ
IAS	Single Pulse Avalanche Current ²	-46	A
P _D	Power Dissipation ($T_c=25^\circ\text{C}$)	4.1	W
	Power Dissipation – Derate above 25°C	0.033	W/°C
T _{STG}	Storage Temperature Range	-55 to 150	°C
T _J	Operating Junction Temperature Range	-55 to 150	°C

Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
R _{θJC}	Thermal Resistance Junction to Case	---	30	°C/W
R _{θJA}	Thermal Resistance Junction to Ambient	---	62	°C/W

Electrical Characteristics ($T_J=25\text{ }^{\circ}\text{C}$, unless otherwise noted)
Off Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}$, $I_D=-250\mu\text{A}$	-60	---	---	V
I_{DSS}	Drain-Source Leakage Current	$V_{DS}=-60\text{V}$, $V_{GS}=0\text{V}$, $T_J=25\text{ }^{\circ}\text{C}$	---	---	-1	uA
		$V_{DS}=-48\text{V}$, $V_{GS}=0\text{V}$, $T_J=125\text{ }^{\circ}\text{C}$	---	---	-10	uA
I_{GSS}	Gate-Source Leakage Current	$V_{GS}=\pm 20\text{V}$, $V_{DS}=0\text{V}$	---	---	± 100	nA

On Characteristics

$R_{DS(ON)}$	Static Drain-Source On-Resistance	$V_{GS}=-10\text{V}$, $I_D=-8\text{A}$	---	23	30	mΩ
		$V_{GS}=-4.5\text{V}$, $I_D=-6\text{A}$	---	28	40	mΩ
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS}=V_{DS}$, $I_D = -250\mu\text{A}$	-1.0	-1.6	-2.5	V
g_{fs}	Forward Transconductance	$V_{DS}=-10\text{V}$, $I_D=-3\text{A}$	---	18	---	S

Dynamic and switching Characteristics

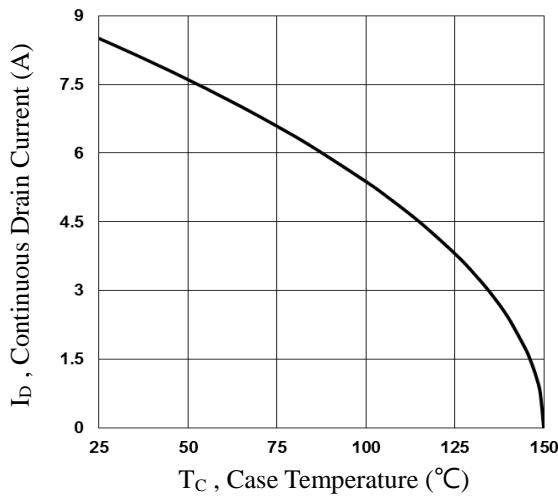
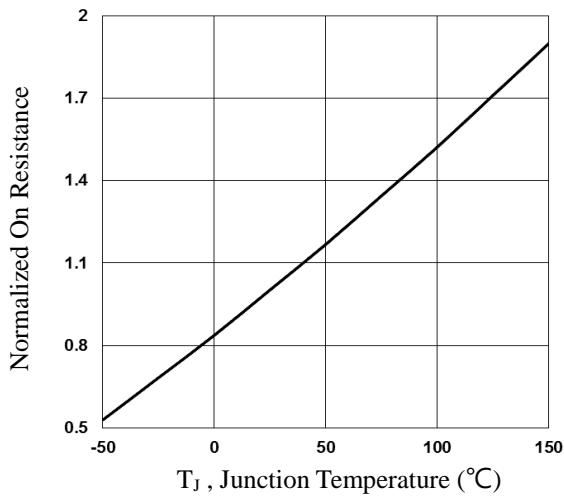
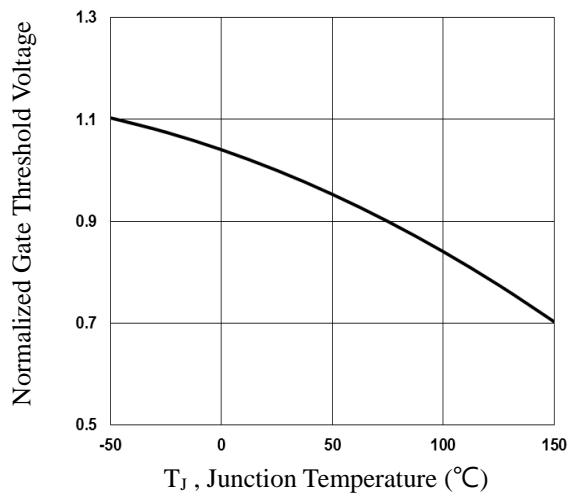
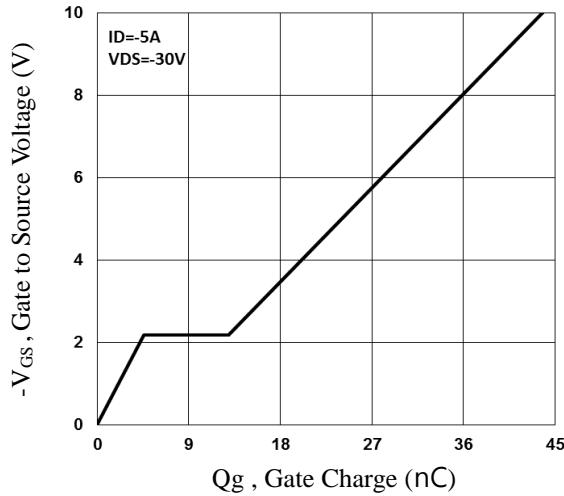
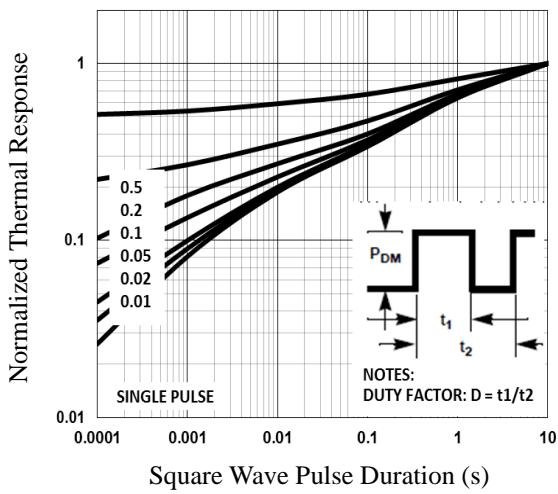
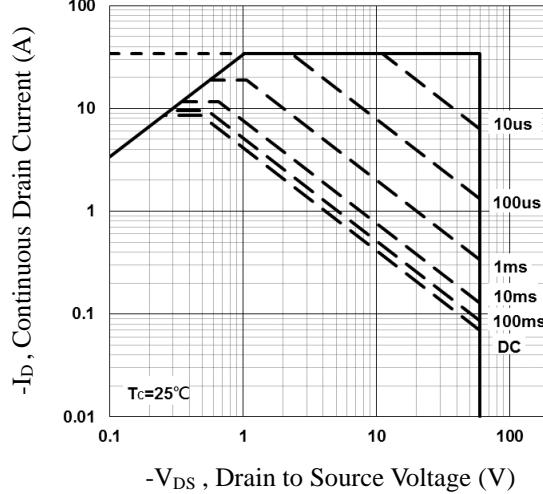
Q_g	Total Gate Charge ^{3, 4}	$V_{DS}=-30\text{V}$, $V_{GS}=-10\text{V}$, $I_D=-5\text{A}$	---	43.8	88	nC
Q_{gs}	Gate-Source Charge ^{3, 4}		---	4.6	9	
Q_{gd}	Gate-Drain Charge ^{3, 4}		---	8.3	17	
$T_{d(on)}$	Turn-On Delay Time ^{3, 4}	$V_{DD}=-30\text{V}$, $V_{GS}=-10\text{V}$, $R_G=6\Omega$ $I_D=-1\text{A}$	---	25	50	ns
T_r	Rise Time ^{3, 4}		---	13.8	28	
$T_{d(off)}$	Turn-Off Delay Time ^{3, 4}		---	148	290	
T_f	Fall Time ^{3, 4}		---	51	100	
C_{iss}	Input Capacitance	$V_{DS}=-25\text{V}$, $V_{GS}=0\text{V}$, $F=1\text{MHz}$	---	2595	3900	pF
C_{oss}	Output Capacitance		---	162	240	
C_{rss}	Reverse Transfer Capacitance		---	115	170	

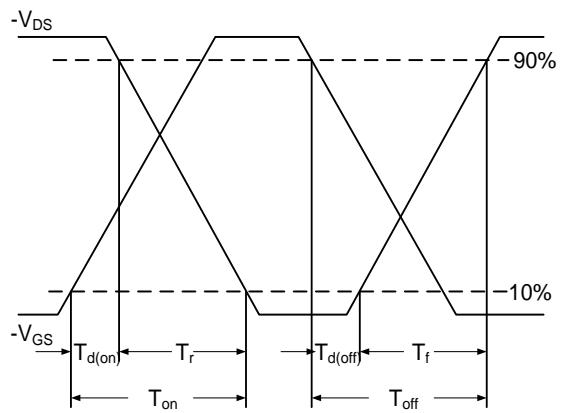
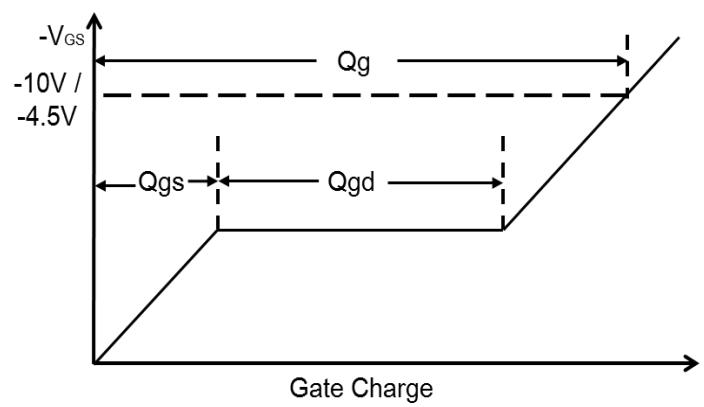
Drain-Source Diode Characteristics and Maximum Ratings

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I_s	Continuous Source Current	$V_G=V_D=0\text{V}$, Force Current	---	---	-8.5	A
			---	---	-17	A
V_{SD}	Diode Forward Voltage	$V_{GS}=0\text{V}$, $I_s=-1\text{A}$, $T_J=25\text{ }^{\circ}\text{C}$	---	---	-1	V
t_{rr}	Reverse Recovery Time	$V_R=-50\text{V}$, $I_s=-5\text{A}$ di/dt=100A/ μs , $T_J=25\text{ }^{\circ}\text{C}$	---	40	---	ns
Q_{rr}	Reverse Recovery Charge		---	30	---	nC

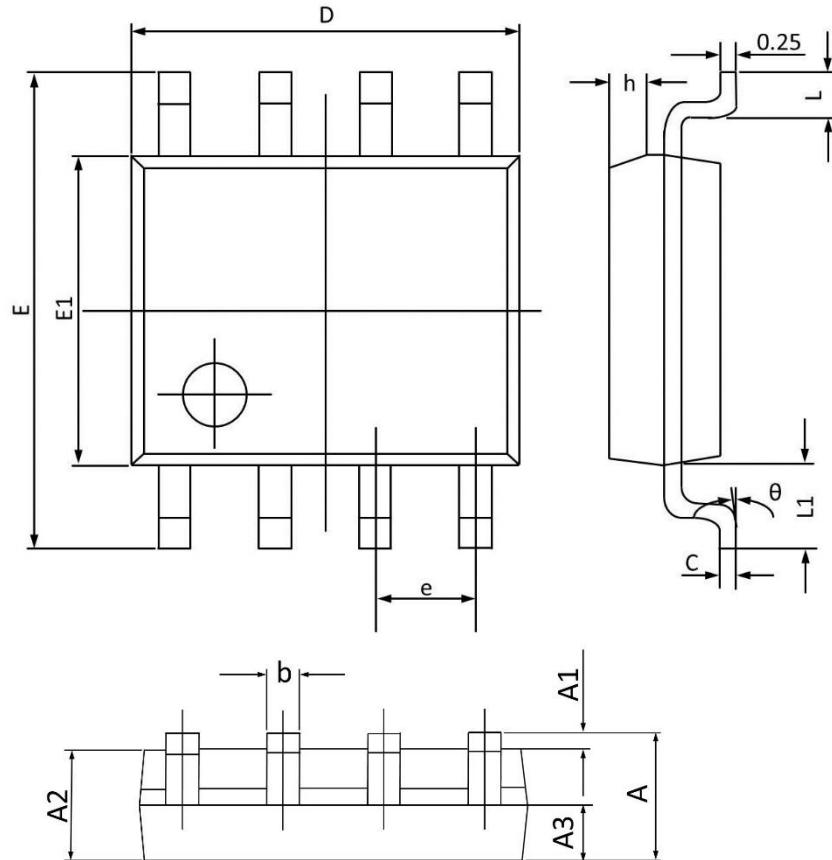
Note :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. $V_{DD}=-25\text{V}$, $V_{GS}=-10\text{V}$, $L=0.1\text{mH}$, $I_{AS}=-46\text{A}$, $R_G=25\Omega$, Starting $T_J=25\text{ }^{\circ}\text{C}$.
3. The data tested by pulsed , pulse width $\leq 300\text{us}$, duty cycle $\leq 2\%$.
4. Essentially independent of operating temperature.


Fig.1 Continuous Drain Current vs. T_c

Fig.2 Normalized RD_{ON} vs. T_J

Fig.3 Normalized V_{th} vs. T_J

Fig.4 Gate Charge Waveform

Fig.5 Normalized Transient Impedance

Fig.6 Maximum Safe Operation Area


Fig.7 Switching Time Waveform

Fig.8 Gate Charge Waveform

SOP8 PACKAGE INFORMATION



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.350	1.800	0.053	0.069
A1	0.050	0.250	0.002	0.010
A2	1.250	1.650	0.049	0.065
A3	0.500	0.700	0.020	0.028
b	0.300	0.510	0.012	0.020
c	0.150	0.260	0.006	0.010
D	4.700	5.100	0.185	0.201
E	5.800	6.200	0.228	0.244
E1	3.700	4.100	0.146	0.161
e	1.270(BSC)		0.050(BSC)	
h	0.250	0.500	0.010	0.020
L	0.400	1.000	0.016	0.039
L1	1.050(BSC)		0.041(BSC)	
θ	0°	8°	0°	8°